

## IN THE CLAIMS

The text of all pending claims, along with their current status, is set forth below.

1. (Currently Amended) A method of testing semiconductor die comprising the acts of:  
~~forming a stack of at least two semiconductor die~~  
a) picking up a first die having a topside and an underside with a die picking tool;  
b) applying adhesive to the underside of the first die, thereby providing an adhesively coated underside of the first die; and  
c) without releasing the first die from the die picking tool, picking up a second die having a topside and an underside by placing the adhesively coated underside of the first die against the topside of the second die, thereby forming a die stack of at least two semiconductor die; and  
after the die stack is formed, testing the semiconductor die in the die stack prior to attaching the semiconductor die to a packaging substrate.
2. (Canceled)
3. (Currently Amended) The method, as set forth in claim 2 1, wherein the first die is thicker than the second die.
4. (Currently Amended) The method, as set forth in claim 2 1, wherein the acts (a), (b), and (c) are performed in the recited order.

5. (Currently Amended) The method, as set forth in claim 2 1, wherein act (b) is performed before act (a).

6. (Currently Amended) The method, as set forth in claim 2 1, comprising the act of applying adhesive to the underside of the second die, thereby providing an adhesively coated underside of the second die.

7. (Original) The method, as set forth in claim 6, comprising the act of without releasing the first die from the picking tool, picking up a third die having a topside and an underside by placing the adhesively coated underside of the second die against the topside of the third die.

8. (Currently Amended) The method, as set forth in claim 1, ~~wherein the act of forming~~  
~~comprises~~ comprising the act of forming ~~a~~ the die stack of at least three semiconductor die.

9. (Currently Amended) The method, as set forth in claim 1, wherein the act of testing comprises the act of:

after the stack is formed, functionally testing the semiconductor die in the die stack prior to attaching the semiconductor die to the packaging substrate.

10. (Currently Amended) The method, as set forth in claim 1, wherein the act of testing comprises the act of:

after the die stack is formed, ~~environmental~~ environmentally testing the semiconductor die in the die stack prior to attaching the semiconductor die to the packaging substrate.

11. (Currently Amended) The method, as set forth in claim 1, comprising the act of coupling the tested die stack to the packaging substrate.
12. (Original) The method, as set forth in claim 1, wherein packaging substrate comprises a tape reel.
13. (Original) The method, as set forth in claim 1, wherein the packaging substrate comprises a film frame.
14. (Original) The method, as set forth in claim 1, wherein the packaging substrate comprises a gel pack.
15. (Original) The method, as set forth in claim 1, wherein the packaging substrate comprises a wafer.
16. (Currently Amended) The method, as set forth in claim 1, comprising the acts of:  
applying a first adhesive between each of the at least two semiconductor die, the first adhesive being curable at a first temperature; and  
applying a second adhesive between the die stack and the packaging substrate, the second adhesive being curable at a second temperature lower than the first temperature.

17. (Currently Amended) The method, as set forth in claim 1, wherein the act of forming a die stack comprises forming a shingle stack.

18. (Currently Amended) The method, as set forth in claim 11, comprising the act of using the tested die stack coupled to the packaging substrate to form an integrated circuit package.

19. (Original) The method, as set forth in claim 18, comprising the act of electrically coupling the integrated circuit package to a processor to form an electronic system.

20. (Original) The method, as set forth in claim 1, wherein at least one of the at least two semiconductor die comprises a memory die.